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## **Transient Voltage Suppression Diodes**

### Surface Mount - 1500W > SMCG-HRA series

### SMCG-HRA Series





### **Agency Approvals**

AGENCY	AGENCY FILE NUMBER
<b>71</b> 2	E230531

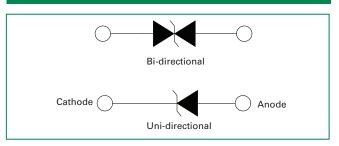
### **Maximum Ratings and Thermal Characteristics** (T<sub>a</sub>=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Peak Pulse Power Dissipation at $T_A$ =25°C by 10/1000 $\mu$ s waveform (Fig.2)(Note 1), (Note 2)	P <sub>PPM</sub>	1500	W
Power Dissipation on infinite heat sink at $T_A$ =50°C	P <sub>M(AV)</sub>	6.5	W
Peak Forward Surge Current, 8.3ms Single Half Sine Wave (Note 3)	I <sub>FSM</sub>	200	А
Maximum Instantaneous Forward Voltage at 100A for Unidirectional only	V <sub>F</sub>	3.5	V
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-65 to 150	°C
Typical Thermal Resistance Junction to Lead	R <sub>wL</sub>	15	°C/W
Typical Thermal Resistance Junction to Ambient	R <sub>uJA</sub>	75	°C/W

#### Notes:

- 1. Non-repetitive current pulse , per Fig. 4 and derated above  $T_{\rm A} = 25^{\circ}{\rm C}$  per Fig. 3.
- 2. Mounted on copper pad area of  $0.31 \times 0.31$ " (8.0  $\times$  8.0mm) to each terminal.
- 3. Measured on 8.3ms single half sine wave or equivalent square wave for unidirectional device only, duty cycle=4 per minute maximum.

### **Functional Diagram**



### **Description**

The SMCG-HRA series is designed specifically to protect sensitive electronic equipment from voltage transients induced by lightning and other transient voltage events.

#### **Features**

- High-Reliability upscreened for critical applications require higher reliability performance and low infant mortality failures.
- · Excellent clamping capability
- Low incremental surge resistance
- Typical I<sub>B</sub> less than 1µA above 12V
- · For surface mounted applications to optimize board space
- L bend lead forming gives best solderbility for Hi reliability application
- Typical failure mode is short from over-specified voltage or current
- Whisker test is conducted based on JEDEC JESD201A per its table 4a and 4c
- IEC-61000-4-2 ESD 15kV(Air), 8kV (Contact)
- ESD protection of data lines in accordance with IEC 61000-4-2 (IEC801-2)

- EFT protection of data lines in accordance with IEC 61000-4-4 (IEC801-4)
- Built-in strain relief
- Fast response time: typically less than 1.0ps from 0V to BV min
- 1500W peak pulse power capability at 10/1000µs waveform, repetition rate (duty cycles):0.01%
- V<sub>BR</sub> @T<sub>J</sub>= V<sub>BR</sub>@25°C x (1+αT  $\times$  (T<sub>1</sub>- 25)) ( $\alpha$  T:Temperature Coefficient, typical value is 0.1%)
- Glass passivated chip junction
- High temperature soldering guaranteed: 260°C/10 seconds at terminals
- Meet MSL level1, per J-STD-020, LF maximun peak of 260°C
- Matte tin lead–free plated
- Halogen free
- RoHS compliant with exemption 7a and 7c-l
- 2nd level interconnect is Pb-free per IPC/JEDEC J-STD-609A.01

### **Applications**

TVS devices are ideal for the protection of I/O Interfaces, V<sub>cc</sub> bus and other vulnerable circuits used in Telecom, Computer, Industrial and Consumer electronic applications.



### **Electrical Characteristics**

Part Number (Uni)	Part Number (Bi)	Mar	king	Reverse Stand off Voltage V <sub>R</sub>	Volta	kdown ge V <sub>BR</sub> s) @ I <sub>T</sub>	Test Current I <sub>T</sub>	Maximum Clamping Voltage V <sub>c</sub> @ I	Maximum Peak Pulse Current I <sub>pp</sub>	Maximum Reverse Leakage I <sub>R</sub> @ V <sub>R</sub>	Agency Approval
		UNI	ВІ	(Volts)	MIN	MAX	(mA)	(V) <sup>PP</sup>	(A) pp	(μ <b>Α</b> )	
SMCG5.0A-HRA	SMCG5.0CA-HRA	GDEH	BDEH	5.0	6.40	7.00	10	9.2	163.0	800	Χ
SMCG6.0A-HRA	SMCG6.0CA-HRA	GDGH	BDGH	6.0	6.67	7.37	10	10.3	145.7	800	X
SMCG6.5A-HRA	SMCG6.5CA-HRA	GDKH	BDKH	6.5	7.22	7.98	10	11.2	134.0	500	X
SMCG7.0A-HRA	SMCG7.0CA-HRA	GDMH	BDMH	7.0	7.78	8.60	10	12.0	125.0	200	X
SMCG7.5A-HRA	SMCG7.5CA-HRA	GDPH	BDPH	7.5	8.33	9.21	1	12.9	116.3	100	X
SMCG8.0A-HRA	SMCG8.0CA-HRA	GDRH	BDRH	8.0	8.89	9.83	1	13.6	110.3	50	X
SMCG8.5A-HRA	SMCG8.5CA-HRA	GDTH	BDTH	8.5	9.44	10.40	1	14.4	104.2	20	X
SMCG9.0A-HRA	SMCG9.0CA-HRA	GDVH	BDVH	9.0	10.00	11.10	1	15.4	97.4	10	X
SMCG10A-HRA	SMCG10CA-HRA	GDXH	BDXH	10.0	11.10	12.30	1	17.0	88.3	5	X
SMCG11A-HRA	SMCG11CA-HRA	GDZH	BDZH	11.0	12.20	13.50	1	18.2	82.5	1	X
SMCG12A-HRA	SMCG12CA-HRA	GEEH	BEEH	12.0	13.30	14.70	1	19.9	75.4	1	X
SMCG13A-HRA	SMCG13CA-HRA	GEGH	BEGH	13.0	14.40	15.90	1	21.5	69.8	1	X
SMCG14A-HRA	SMCG14CA-HRA	GEKH	BEKH BEMH	14.0 15.0	15.60 16.70	17.20	1	23.2	64.7	1	X
SMCG15A-HRA SMCG16A-HRA	SMCG15CA-HRA SMCG16CA-HRA	GEMH GEPH	BEPH	16.0	17.80	18.50 19.70	1	26.0	61.5 57.7	1	X
SMCG17A-HRA	SMCG17CA-HRA	GERH	BERH	17.0	18.90	20.90	1	27.6	54.4	1	X
SMCG18A-HRA	SMCG18CA-HRA	GETH	BETH	18.0	20.00	22.10	1	29.2	51.4	1	X
SMCG20A-HRA	SMCG20CA-HRA	GEVH	BEVH	20.0	22.20	24.50	1	32.4	46.3	1	X
SMCG22A-HRA	SMCG22CA-HRA	GEXH	BEXH	22.0	24.40	26.90	1	35.5	42.3	1	X
SMCG24A-HRA	SMCG24CA-HRA	GEZH	BEZH	24.0	26.70	29.50	1	38.9	38.6	1	X
SMCG26A-HRA	SMCG26CA-HRA	GFEH	BFEH	26.0	28.90	31.90	1	42.1	35.7	1	X
SMCG28A-HRA	SMCG28CA-HRA	GFGH	BFGH	28.0	31.10	34.40	1	45.4	33.1	1	X
SMCG30A-HRA	SMCG30CA-HRA	GFKH	BFKH	30.0	33.30	36.80	1	48.4	31.0	1	X
SMCG33A-HRA	SMCG33CA-HRA	GFMH	BFMH	33.0	36.70	40.60	1	53.3	28.2	1	X
SMCG36A-HRA	SMCG36CA-HRA	GFPH	BFPH	36.0	40.00	44.20	1	58.1	25.9	1	X
SMCG40A-HRA	SMCG40CA-HRA	GFRH	BFRH	40.0	44.40	49.10	1	64.5	23.3	1	X
SMCG43A-HRA	SMCG43CA-HRA	GFTH	BFTH	43.0	47.80	52.80	1	69.4	21.7	1	X
SMCG45A-HRA	SMCG45CA-HRA	GFVH	BFVH	45.0	50.00	55.30	1	72.7	20.6	1	X
SMCG48A-HRA	SMCG48CA-HRA	GFXH	BFXH	48.0	53.30	58.90	1	77.4	19.4	1	X
SMCG51A-HRA	SMCG51CA-HRA	GFZH	BFZH	51.0	56.70	62.70	1	82.4	18.2	1	X
SMCG54A-HRA	SMCG54CA-HRA	GGEH	BGEH	54.0	60.00	66.30	1	87.1	17.3	1	Χ
SMCG58A-HRA	SMCG58CA-HRA	GGGH	BGGH	58.0	64.40	71.20	1	93.6	16.1	1	Χ
SMCG60A-HRA	SMCG60CA-HRA	GGKH	BGKH	60.0	66.70	73.70	1	96.8	15.5	1	X
SMCG64A-HRA	SMCG64CA-HRA	GGMH	BGMH	64.0	71.10	78.60	1	103.0	14.6	1	X
SMCG70A-HRA	SMCG70CA-HRA	GGPH	BGPH	70.0	77.80	86.00	1	113.0	13.3	1	X
SMCG75A-HRA	SMCG75CA-HRA	GGRH	BGRH	75.0	83.30	92.10	1	121.0	12.4	1	X
SMCG78A-HRA	SMCG78CA-HRA	GGTH	BGTH	78.0	86.70	95.80	1	126.0	11.9	1	X
SMCG85A-HRA	SMCG85CA-HRA	GGVH	BGVH	85.0	94.40	104.00	1	137.0	11.0	1	X
SMCG90A-HRA	SMCG90CA-HRA	GGXH	BGXH	90.0	100.00	111.00	1	146.0	10.3	1	X
SMCG100A-HRA	SMCG100CA-HRA	GGZH	BGZH	100.0	111.00	123.00	1	162.0	9.3	1	X
SMCG110A-HRA	SMCG110CA-HRA	GHEH	BHEH	110.0	122.00	135.00	1	177.0	8.5	1	X
SMCG120A-HRA	SMCG120CA-HRA	GHGH	BHGH	120.0	133.00	147.00	1	193.0	7.8	1	X

Note

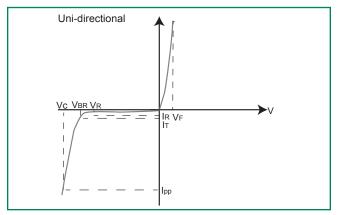
1. For bidirectional type having  $\rm V_{_{\rm R}}$  of 10 volts and less, the  $\rm I_{_{\rm R}}$  limit is double.

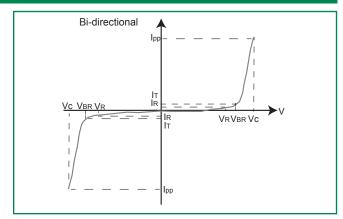
### **Screen Process**

100% vision inspection	MIL-STD-750 method 2074
100%High Temperature Storage Life (168hrs,175C)	MIL-STD-750 method 1031
100% X-RAY inspection	MIL-STD-750 method 2076
100% Temperature cycle test (-55-150C, 20 cycles, dwell time 15 min)	MIL-STD-750 method 1051
100% Reflow (2x)	JEDEC J-STD-020
100% surge test (2x)	MIL-STD-750 method 4066
100% HTRB(150C, Bias=VR(80% breakdown voltage), 96hrs),for Bidirection products, 96hrs for each direction	MIL-STD-750 method 1038
Final electrical test( 100% 3 sigma limit, 100% dynamic test and PAT limit)	MIL-STD-750 method 4016.4021.4011

Note: Up-screen program can be specified by customer's request via contacting Littelfuse service

### **I-V Curve Characteristics**

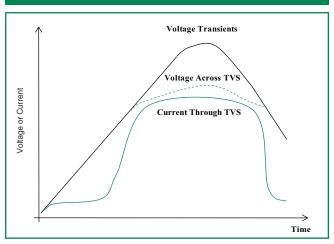




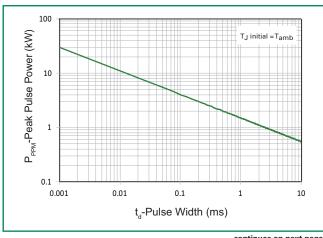
- $\mathbf{P}_{_{\mathbf{PPM}}}$  Peak Pulse Power Dissipation Max power dissipation
- V. Stand-off Voltage Maximum voltage that can be applied to the TVS without operation
- V<sub>ss</sub> Breakdown Voltage -- Maximum voltagethat flows though the TVS at a specified test current (I,)
- V<sub>c</sub> Clamping Voltage Peak voltage measured across the TVS at a specified Ippm (peak impulse current)
- I, Reverse Leakage Current -- Current measured at V,
- V<sub>F</sub> Forward Voltage Drop for Uni-directional

### Ratings and Characteristic Curves (T<sub>A</sub>=25°C unless otherwise noted)

Figure 1 - TVS Transients Clamping Waveform







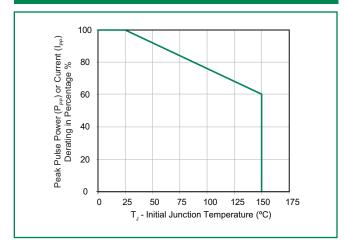
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### **Transient Voltage Suppression Diodes**

Surface Mount – 1500W > SMCG-HRA series

### Ratings and Characteristic Curves (T<sub>A</sub>=25°C unless otherwise noted) (Continued)

Figure 3 - Peak Pulse Power Derating Curve



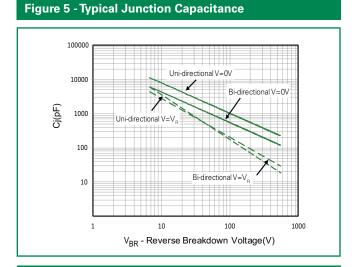


Figure 7 - Maximum Non-Repetitive Peak Forward **Surge Current Uni-Directional Only** 

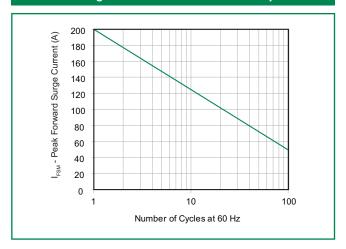


Figure 4 - Pulse Waveform

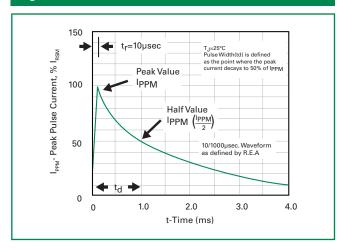
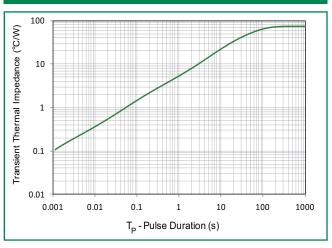
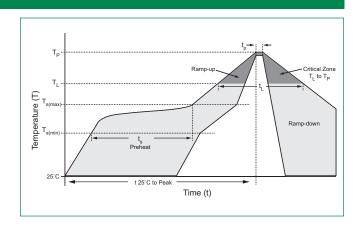


Figure 6 - Typical Transient Thermal Impedance



### **Soldering Parameters**

Reflow Co	ndition	Lead–free assembly	
	-Temperature Min (T <sub>s(min)</sub> )	150°C	
Pre Heat	-Temperature Max (T <sub>s(max)</sub> )	200°C	
	-Time (min to max) (t <sub>s</sub> )	60 - 120 secs	
Average ra	amp up rate (LiquidusTemp k	3°C/second max	
T <sub>S(max)</sub> to T <sub>L</sub> - Ramp-up Rate		3°C/second max	
Reflow	-Temperature (T <sub>L</sub> ) (Liquidus)	217°C	
Reliow	-Time (min to max) (t <sub>s</sub> )	60 – 150 seconds	
PeakTemp	erature (T <sub>P</sub> )	260 <sup>+0/-5</sup> °C	
Time with Temperatu	in 5°C of actual peak ure (t <sub>p</sub> )	30 seconds	
Ramp-dov	vn Rate	6°C/second max	
Time 25°C	to peakTemperature (T <sub>P</sub> )	8 minutes Max.	
Do not exc	ceed	260°C	



### **Physical Specifications**

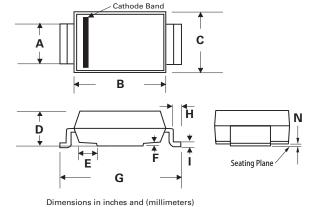
Weight	0.007 ounce, 0.21 grams
Case	JEDEC DO-215AB. Molded plastic body over glass passivated junction
Polarity	Color band denotes positive end (cathode) except Bidirectional.
Terminal	Matte Tin-plated leads, Solderable per JESD22-B102

### **Environmental Specifications**

High Temp. Storage	JESD22-A103
нткв	JESD22-A108
Thermal Shock	JESD22-A106
MSL	JEDEC-J-STD-020, Level 1
H3TRB	JESD22-A101
RSH	JESD22-A111

### **Dimensions**

### DO-215AB (SMCG)



В	0.260	0.280	6.600	7.110
С	0.220	0.245	5.590	6.220
D	0.075	0.095	1.900	2.410
E	0.038	0.058	0.970	1.470
F	-	0.020	-	0.510
G	0.380	0.400	9.640	10.160
Н	0.024	0.040	0.610	1.020
I	0.006	0.016	0.150	0.410
J	-	0.050	-	1.270
K	-	0.310	-	7.870
L	_	0.050	_	1.270

0.125

0.008

Inches

Max

0.125

Min

0.115

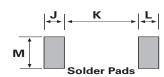
0.002

Dimensions

Α

Μ

Ν



0.050

Millimeters

Max

3.170

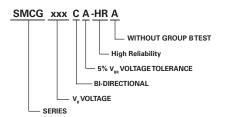
3.170

0.200

Min

2.920

### **Part Numbering System**



### Part Marking System



### **Packaging**

Part number	Component Package	Quantity Packaging Option		Packaging Specification
SMCGxxxXX-HRA	DO-215AB	1500	Tape & Reel – 24mm tape /13" reel	EIA STD RS-481

### **Tape and Reel Specification**

